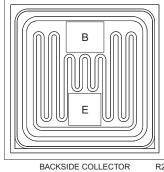


CP310-CMPTA42 NPN - High Voltage Transistor Die

The CP310-CMPTA42 is a silicon NPN transistor designed for high voltage applications.



Die Size	26 x 26 MILS	
Die Thickness	9.0 MILS	
Base Bonding Pad Size	6.1 x 4.9 MILS	
Emitter Bonding Pad Size	5.2 x 5.2 MILS	
Top Side Metalization	AI – 30,000Å	
Back Side Metalization	Au – 9,000Å	
Scribe Alley Width	2.2 MILS	
Wafer Diameter	5 INCHES	
Gross Die Per Wafer	25,214	
2		

MECHANICAL SPECIFICATIONS:

MAXIMUM F	RATINGS: (T _A =25°C)	SYMBOL	300	
	8	V _{CBO}	300	V
Collector-Emitter Voltage		VCEO		-
Emitter-Base Voltage		V _{EBO}	6.0	V
Continuous Collector Current		IС	500	mA
Operating and Storage Junction Temperature		T _{J,} T _{stg}	-65 to +150	°C
ELECTRICA SYMBOL I _{CBO}	L CHARACTERISTICS: $(T_A=25^{\circ}C)$ TEST CONDITIONS $V_{CB}=200V$	MIN	MAX 100	UNITS nA
I _{EBO}	V _{EB} =6.0V		100	nA
BVCBO	I _C =100μΑ	300		V
BVCEO	I _C =1.0mA	300		V
BVEBO	Ι _Ε =100μΑ	6.0		V
V _{CE(SAT)}	I _C =20mA, I _B =2.0mA		0.5	V
V _{BE(SAT)}	I _C =20mA, I _B =2.0mA		0.9	V
h _{FE}	V _{CE} =10V, I _C =1.0mA	25		
h _{FE}	V _{CE} =10V, I _C =10mA	40		
h _{FE}	V _{CE} =10V, I _C =30mA	40		
f _T	V _{CE} =20V, I _C =10mA, f=100MHz	50		MHz
Cob	V_{CB} =20V, I _E =0, f=1.0MHz		6.0	pF

R0 (9-May 2016)

CP310-CMPTA42 Typical Electrical Characteristics

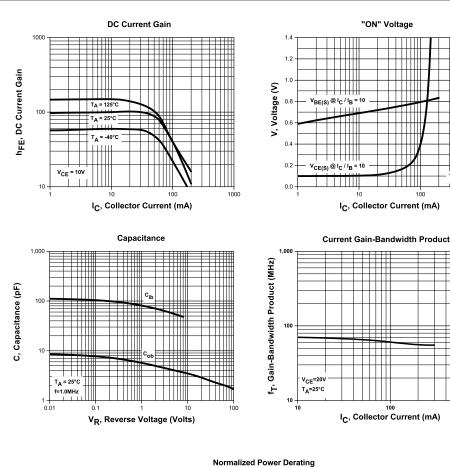


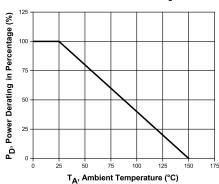
www.centralsemi.com

T_A = 25°C

1000

1,000

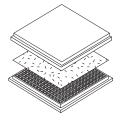






BARE DIE PACKING OPTIONS



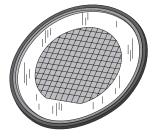


BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

ss your design challenges.

· Custom product packing

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA Main Tel: (631) 435-1110 Main Fax: (631) 435-1824 Support Team Fax: (631) 435-3388 www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

Worldwide Distributors: www.centralsemi.com/wwdistributors

For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: <u>www.centralsemi.com/terms</u>

